

L Number	Hits	Search Text	DB	Time stamp
1	313	(burn adj in) and test	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:16
2	48	((burn adj in) and test) and 365/201	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:18
3	885	(semiconductor adj chip\$1) and (test adj mode)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:20
4	395	((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:20
5	9	((((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)) and (burn adj in)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:21
6	315	((((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)) and single	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:23
7	9	((((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)) and (single adj package)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:31
8	24	(((((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)) and single) and (test adj control adj circuit)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 11:34
9	104	((((semiconductor adj chip\$1) and (test adj mode)) and (control adj circuit)) and 365/201	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 12:12
10	190	(different adj manufacturing adj process\$2) and test	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 12:13
11	7	((different adj manufacturing adj process\$2) and test) and (single adj package)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 12:13
12	1	((different adj manufacturing adj process\$2) and test) and (test adj control)	USPAT; EPO; JPO; DERWENT; USOCR	2004/09/18 12:14